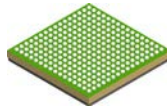


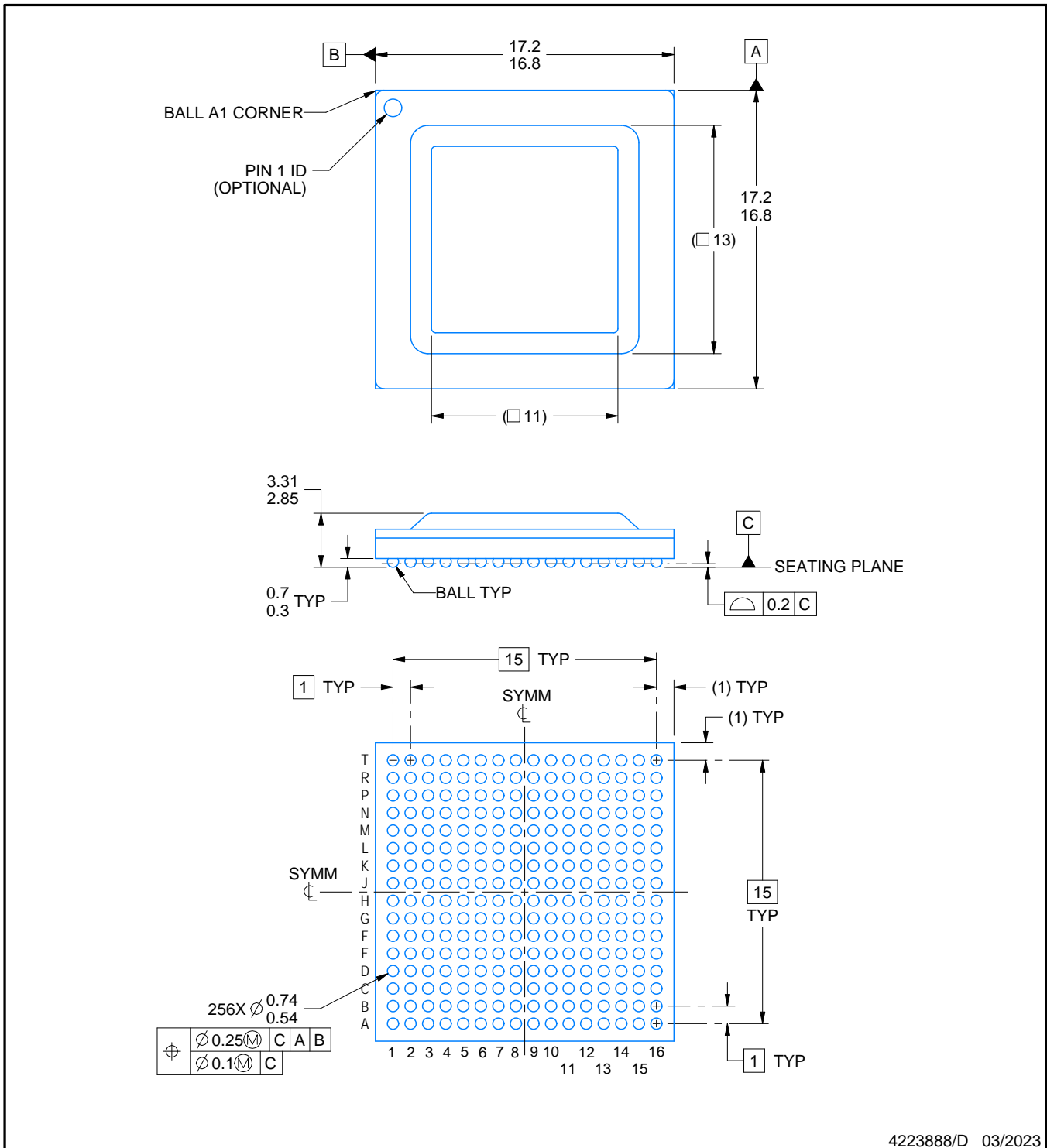
ACF0256A



PACKAGE OUTLINE

FCBGA - 3.31 mm max height

BALL GRID ARRAY



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NOTES:

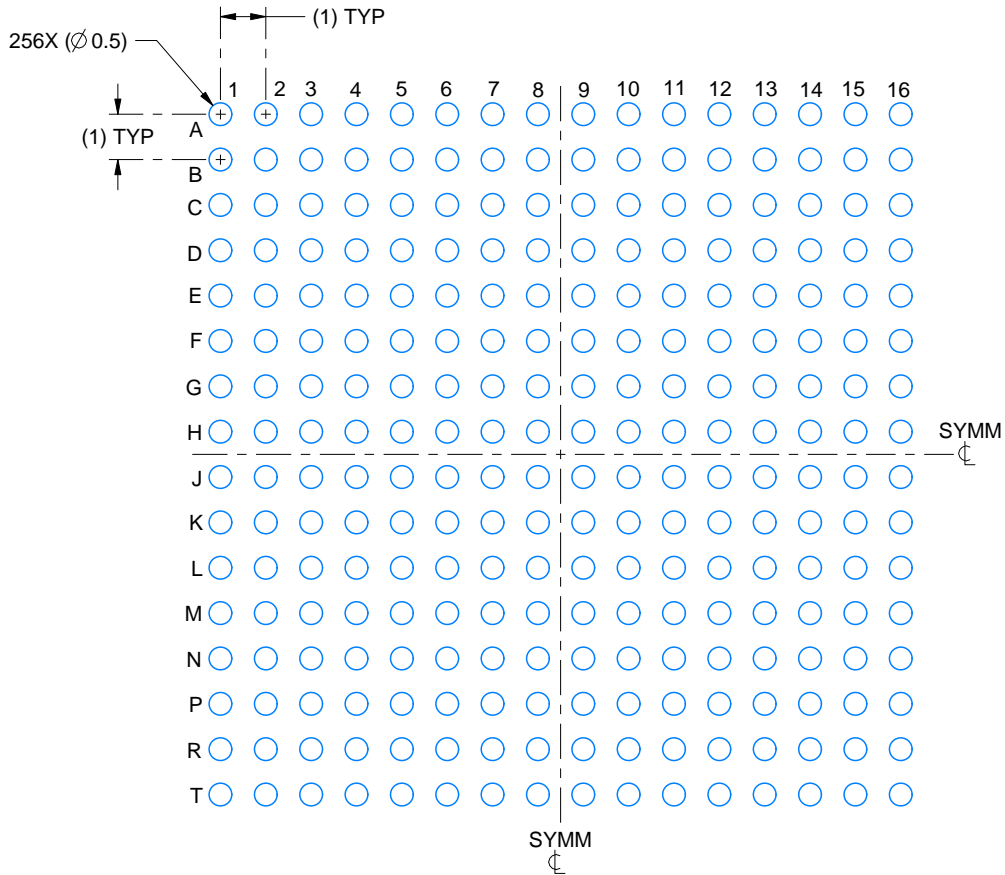
- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- Pb-Free die bump and solder ball.
- The lids are electrically floating (e.g. not tied to GND).

EXAMPLE BOARD LAYOUT

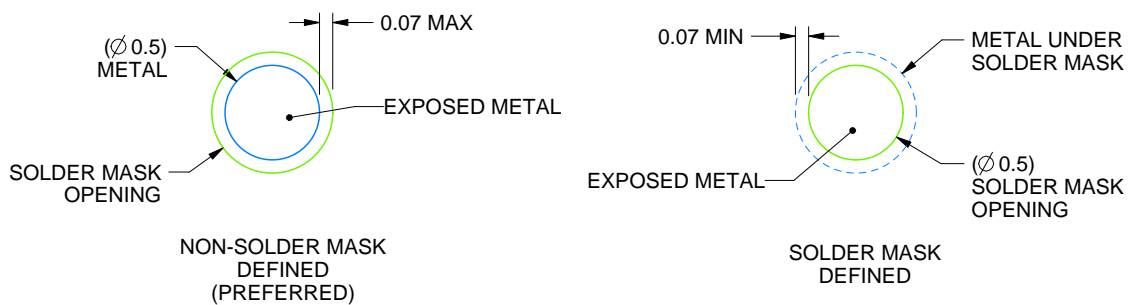
ACF0256A

FCBGA - 3.31 mm max height

BALL GRID ARRAY



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:6X



SOLDER MASK DETAILS
NOT TO SCALE

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NOTES: (continued)

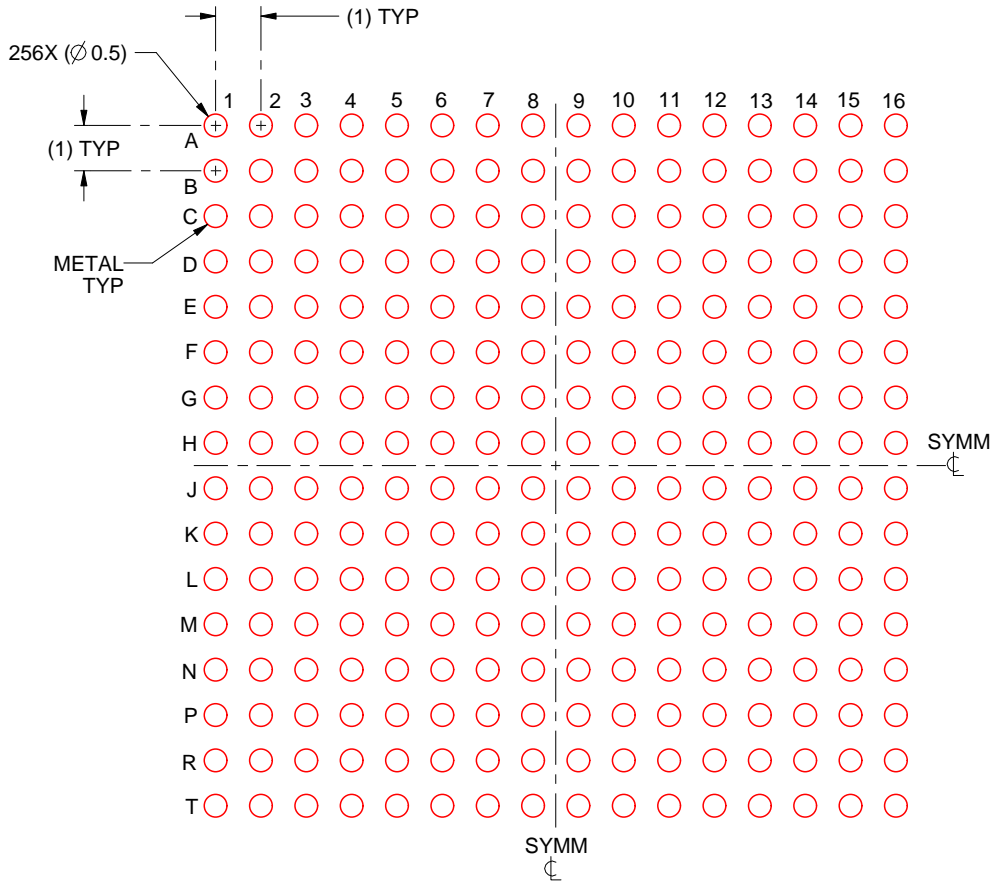
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SPRU811 (www.ti.com/lit/spru811).

EXAMPLE STENCIL DESIGN

ACF0256A

FCBGA - 3.31 mm max height

BALL GRID ARRAY



SOLDER PASTE EXAMPLE
BASED ON 0.15 mm THICK STENCIL
SCALE: 6X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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